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International
IOR Rectifier

PD - 95035

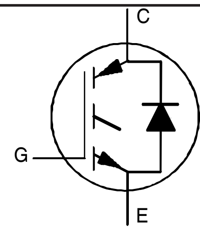
IRG4RC10KDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Short Circuit Rated UltraFast IGBT

Features

- Short Circuit Rated UltraFast: Optimized for high operating frequencies >5.0 kHz , and Short Circuit Rated to 10µs @ 125°C, V_{GE} = 15V
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-252AA package
- Lead-Free



n-channel

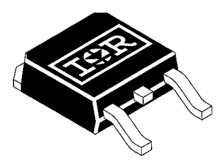
V_{CES} = 600V

$V_{CE(on)\ typ.}$ = 2.39V

@V_{GE} = 15V, I_C = 5.0A

Benefits

- Latest generation 4 IGBT's offer highest power density motor controls possible
- HEXFRED™ diodes optimized for performance with IGBTs. Minimized recovery characteristics reduce noise, EMI and switching losses
- For hints see design tip 97003



D-PAK
TO-252AA

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
I_C @ T_C = 25°C	Continuous Collector Current	9.0	A
I_C @ T_C = 100°C	Continuous Collector Current	5.0	
I_{CM}	Pulsed Collector Current ①	18	
I_{LM}	Clamped Inductive Load Current ②	18	
I_F @ T_C = 100°C	Diode Continuous Forward Current	4.0	
I_{FM}	Diode Maximum Forward Current	16	
t_{sc}	Short Circuit Withstand Time	10	µs
V_{GE}	Gate-to-Emitter Voltage	± 20	V
P_D @ T_C = 25°C	Maximum Power Dissipation	38	W
P_D @ T_C = 100°C	Maximum Power Dissipation	15	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	——	3.3	°C/W
$R_{\theta JC}$	Junction-to-Case - Diode	——	7.0	
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)*	——	50	
Wt	Weight	0.3 (0.01)	——	g (oz)

* When mounted on 1" square PCB (FR-4 or G-10 Material).
For recommended footprint and soldering techniques refer to application note #AN-994

2/20/04

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltageƒ	600	—	—	V	V_{GE} = 0V, I_C = 250µA	
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.58	—	V/°C	V_{GE} = 0V, I_C = 1.0mA	
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	2.39	2.62	V	I_C = 5.0A	V_{GE} = 15V
		—	3.25	—		I_C = 9.0A	See Fig. 2, 5
		—	2.63	—		I_C = 5.0A, T_J = 150°C	
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.5		V_{CE} = V_{GE}, I_C = 250µA	
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/°C	V_{CE} = V_{GE}, I_C = 250µA	
g_{fe}	Forward Transconductance „	1.2	1.8	—	S	V_{CE} = 50V, I_C = 5.0A	
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	µA	V_{GE} = 0V, V_{CE} = 600V	
		—	—	1000		V_{GE} = 0V, V_{CE} = 600V, T_J = 150°C	
V_{FM}	Diode Forward Voltage Drop	—	1.5	1.8	V	I_C = 4.0A	See Fig. 13
		—	1.4	1.7		I_C = 4.0A, T_J = 150°C	
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions		
Q_g	Total Gate Charge (turn-on)	—	19	29	nC	I_C = 5.0A		
Q_{ge}	Gate - Emitter Charge (turn-on)	—	2.9	4.3		V_{CC} = 400V	See Fig.8	
Q_{gc}	Gate - Collector Charge (turn-on)	—	9.8	15		V_{GE} = 15V		
$t_{d(on)}$	Turn-On Delay Time	—	49	—	ns			
t_r	Rise Time	—	28	—		T_J = 25°C		
$t_{d(off)}$	Turn-Off Delay Time	—	97	150		I_C = 5.0A, V_{CC} = 480V		
t_f	Fall Time	—	140	210		V_{GE} = 15V, R_G = 100Ω		
E_{on}	Turn-On Switching Loss	—	0.25	—	mJ	Energy losses include "tail"		
E_{off}	Turn-Off Switching Loss	—	0.14	—		and diode reverse recovery		
E_{ts}	Total Switching Loss	—	0.39	0.48		See Fig. 9,10,14		
t_{sc}	Short Circuit Withstand Time	10	—	—	µs	V_{CC} = 360V, T_J = 125°C		
						V_{GE} = 15V, R_G = 100Ω , V_{CPK} < 500V		
$t_{d(on)}$	Turn-On Delay Time	—	46	—	ns	T_J = 150°C,	See Fig. 10,11,14	
t_r	Rise Time	—	32	—		I_C = 5.0A, V_{CC} = 480V		
$t_{d(off)}$	Turn-Off Delay Time	—	100	—		V_{GE} = 15V, R_G = 100Ω		
t_f	Fall Time	—	310	—		Energy losses include "tail"		
E_{ts}	Total Switching Loss	—	0.56	—	mJ	and diode reverse recovery		
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package		
C_{ies}	Input Capacitance	—	220	—	pF	V_{GE} = 0V		
C_{oes}	Output Capacitance	—	29	—		V_{CC} = 30V	See Fig. 7	
C_{res}	Reverse Transfer Capacitance	—	7.5	—		ƒ = 1.0MHz		
t_{rr}	Diode Reverse Recovery Time	—	28	42	ns	T_J = 25°C	See Fig.	
		—	38	57		T_J = 125°C	14	I_F = 4.0A
I_{rr}	Diode Peak Reverse Recovery Current	—	2.9	5.2	A	T_J = 25°C	See Fig.	
		—	3.7	6.7		T_J = 125°C	15	V_R = 200V
Q_{rr}	Diode Reverse Recovery Charge	—	40	60	nC	T_J = 25°C	See Fig.	
		—	70	105		T_J = 125°C	16	di/dt = 200A/µs
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery	—	280	—	A/µs	T_J = 25°C	See Fig.	
	During t_b	—	235	—		T_J = 125°C	17	

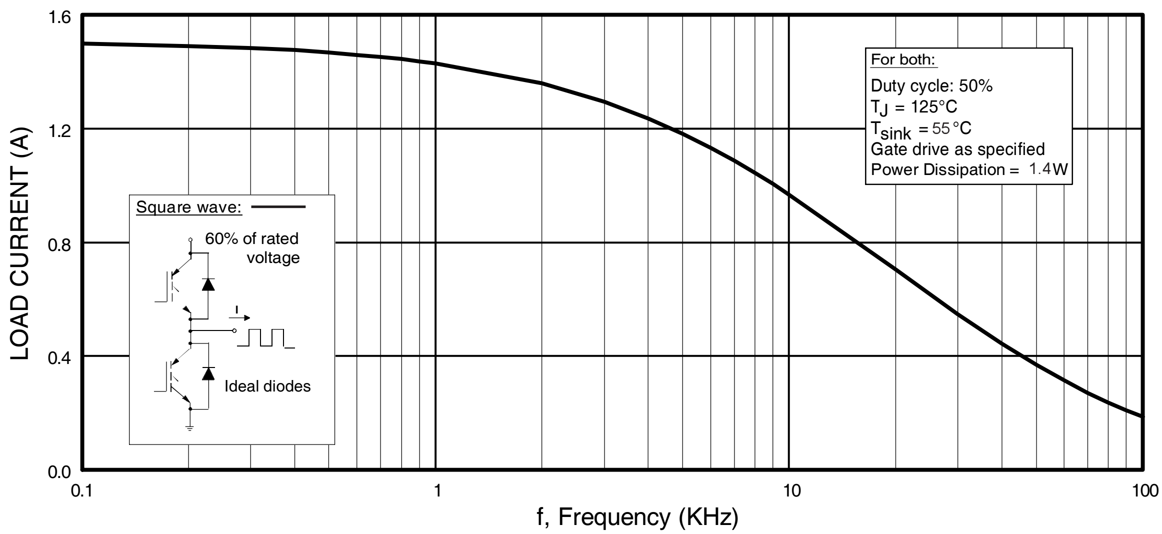


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

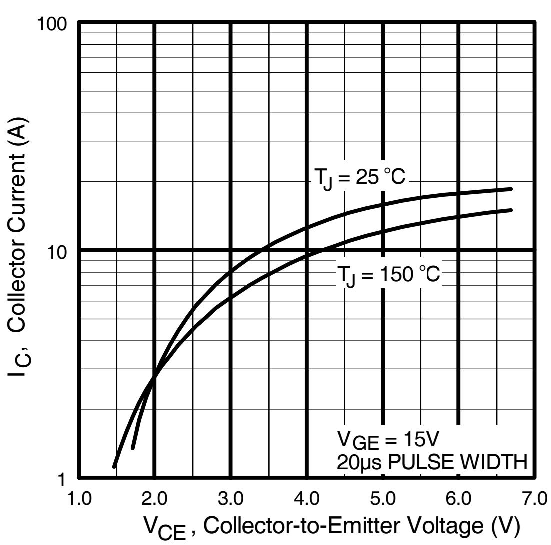


Fig. 2 - Typical Output Characteristics

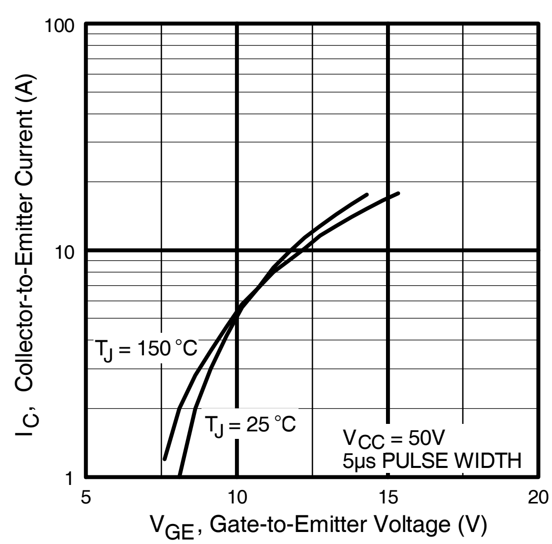


Fig. 3 - Typical Transfer Characteristics

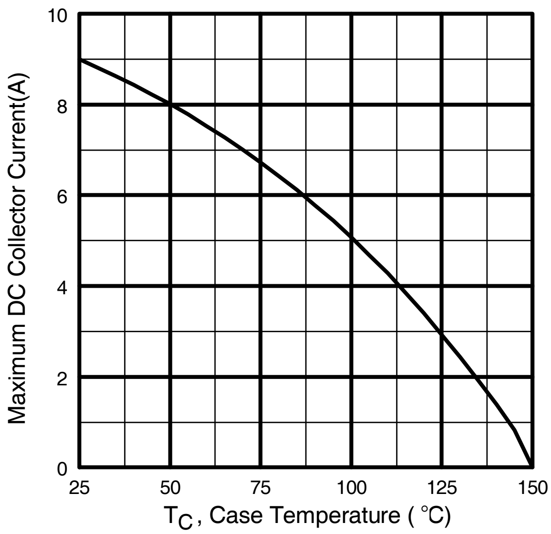


Fig. 4 - Maximum Collector Current vs. Case Temperature

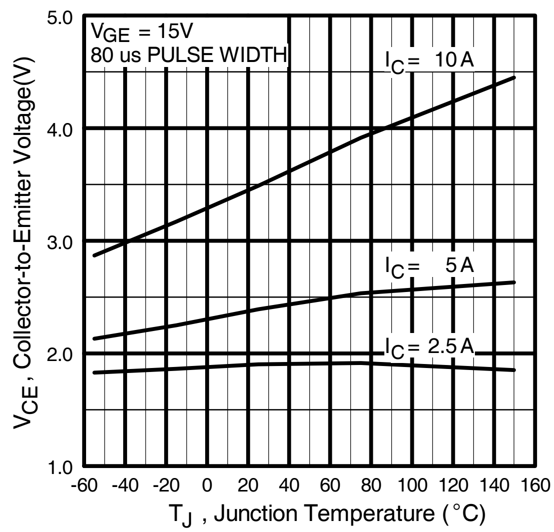


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

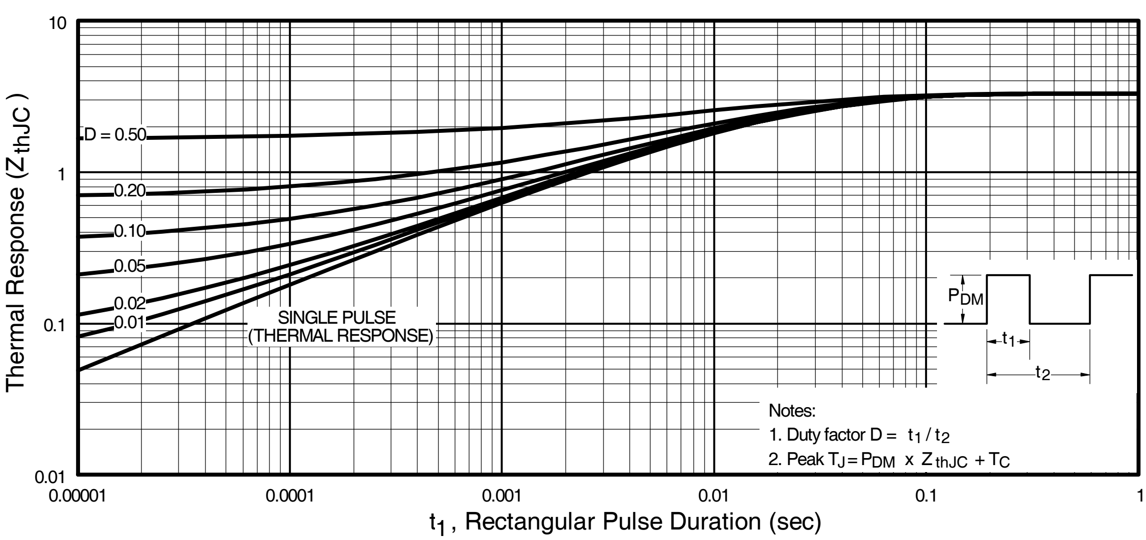


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

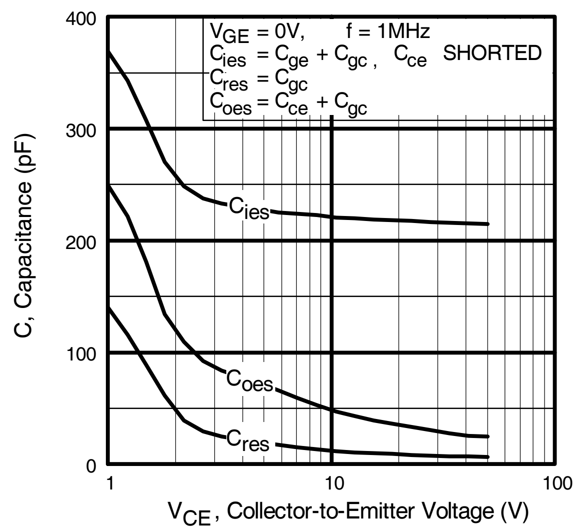


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

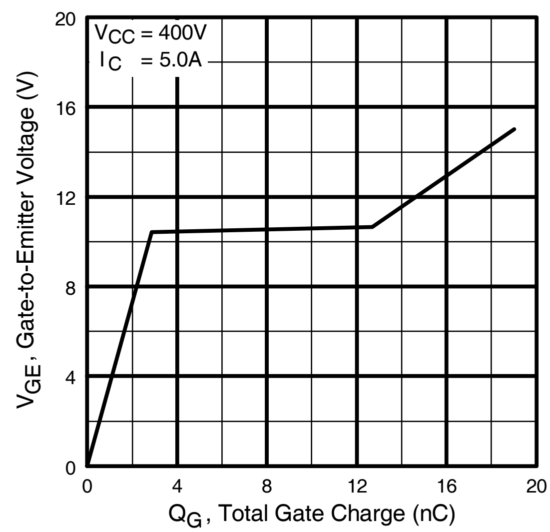


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

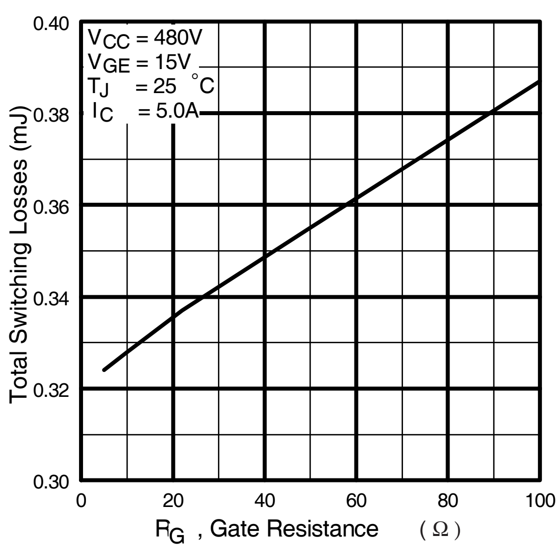


Fig. 9 - Typical Switching Losses vs. Gate Resistance

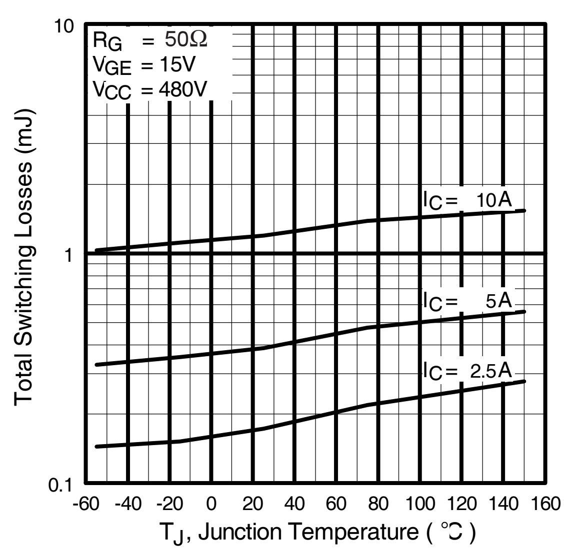


Fig. 10 - Typical Switching Losses vs. Junction Temperature

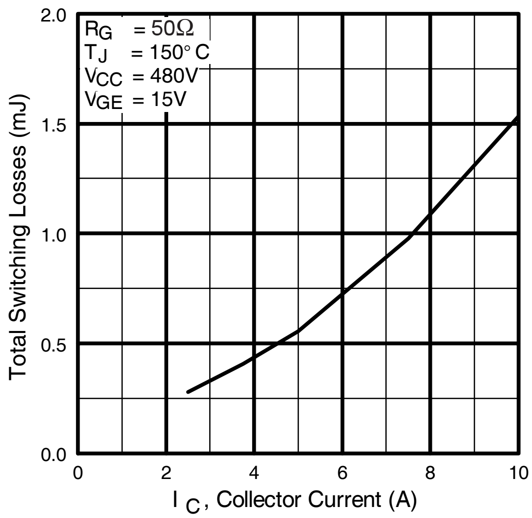


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

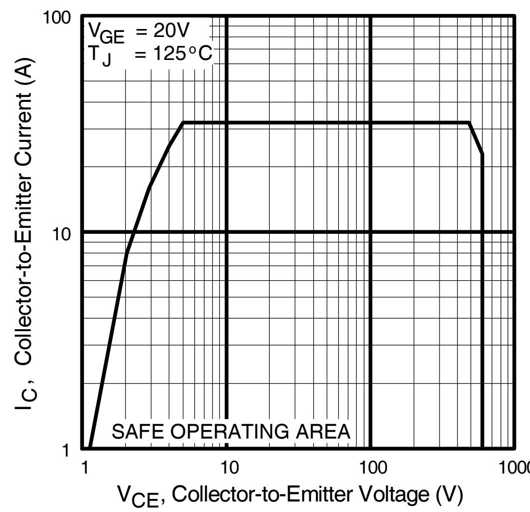


Fig. 12 - Turn-Off SOA

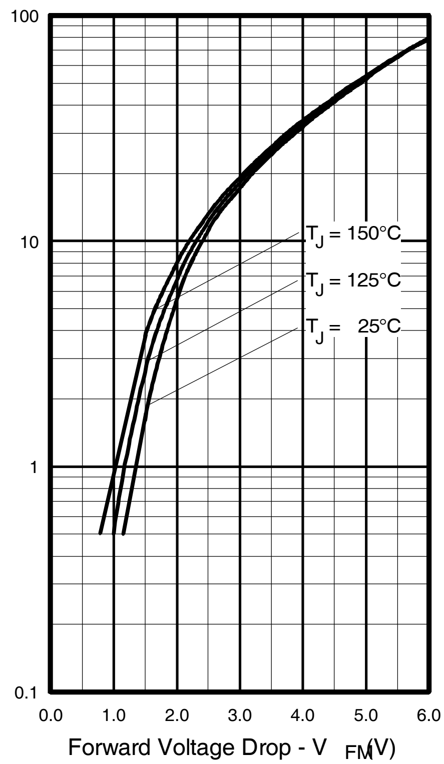


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

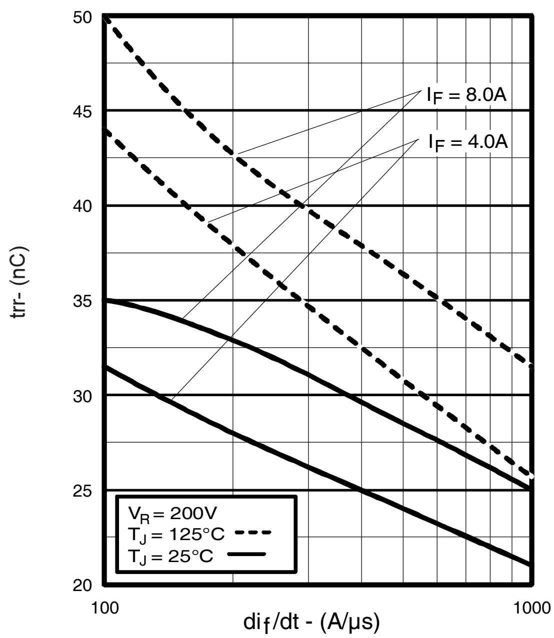


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

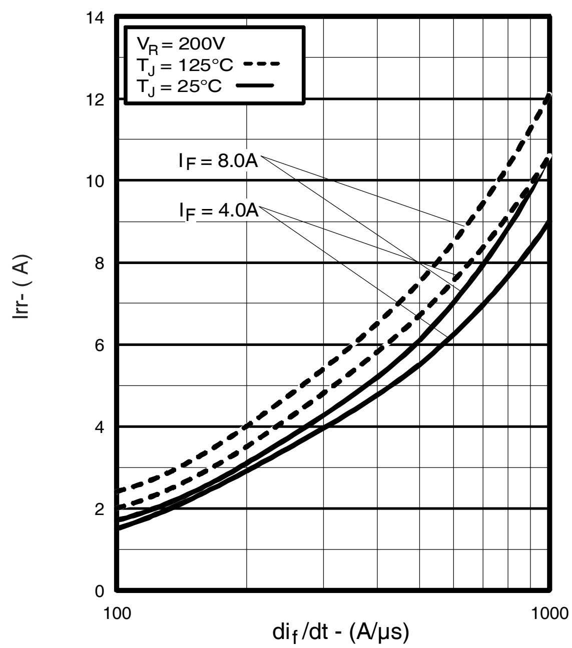


Fig. 15 - Typical Recovery Current vs. di_f/dt

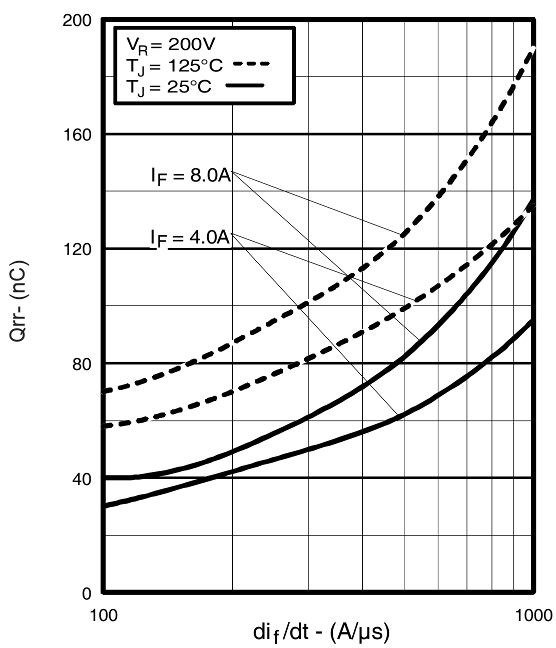


Fig. 16 - Typical Stored Charge vs. di_f/dt

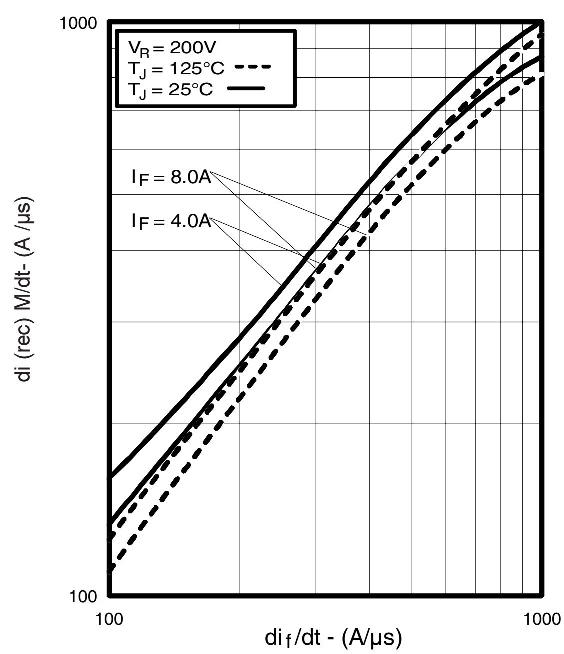


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt,

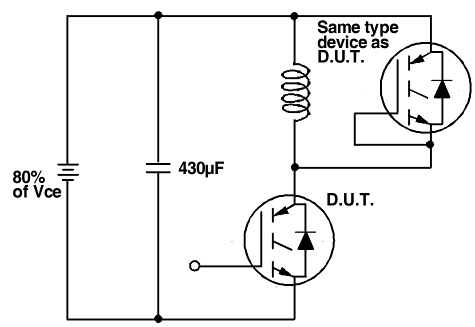


Fig. 18a - Test Circuit for Measurement of I_{LM}, E_{on}, $E_{off(diode)}$, t_{rr}, Q_{rr}, I_{rr}, $t_{d(on)}$, t_r, $t_{d(off)}$, t_f

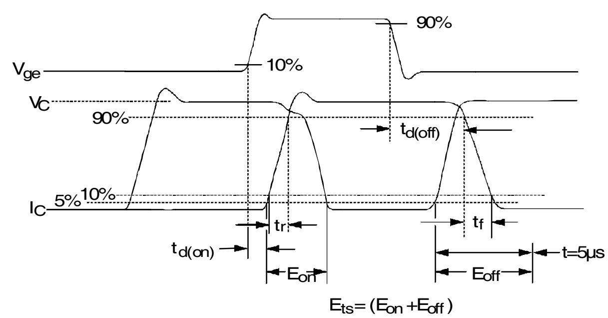


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off}, $t_{d(off)}$, t_f

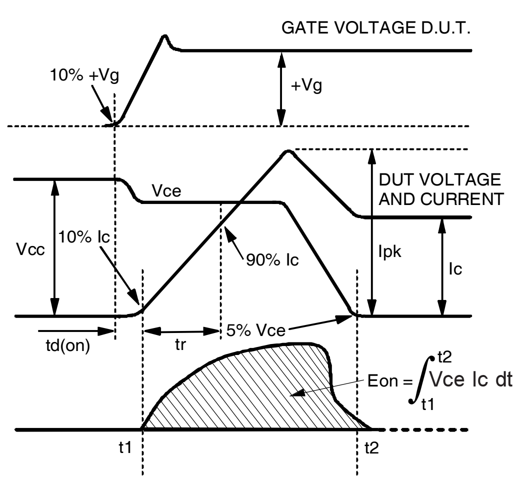


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on}, $t_{d(on)}$, t_r

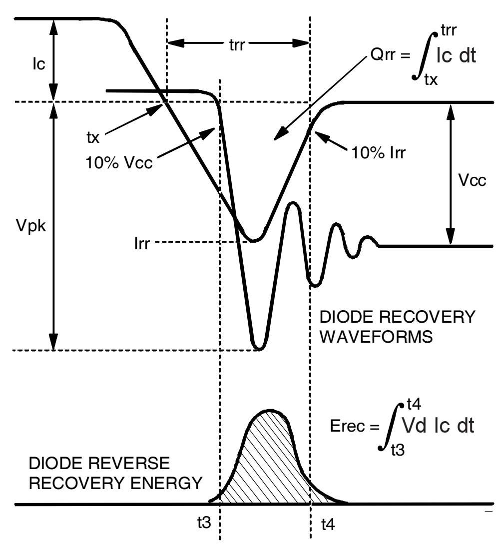


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec}, t_{rr}, Q_{rr}, I_{rr}

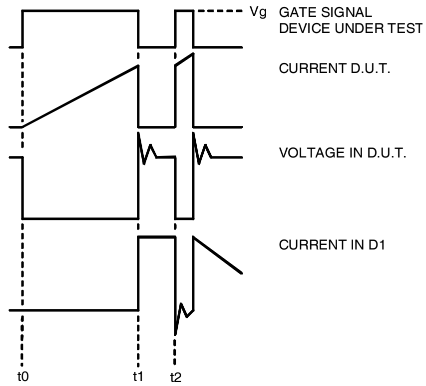


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

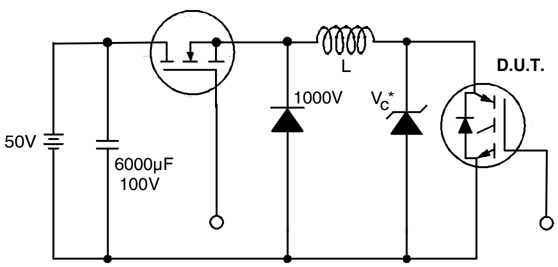


Figure 19. Clamped Inductive Load Test Circuit

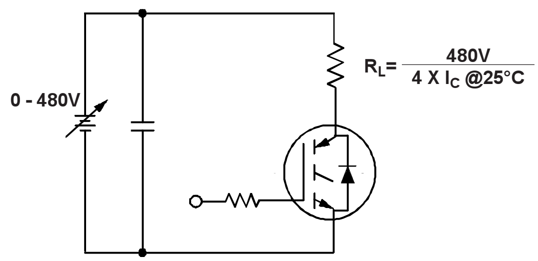
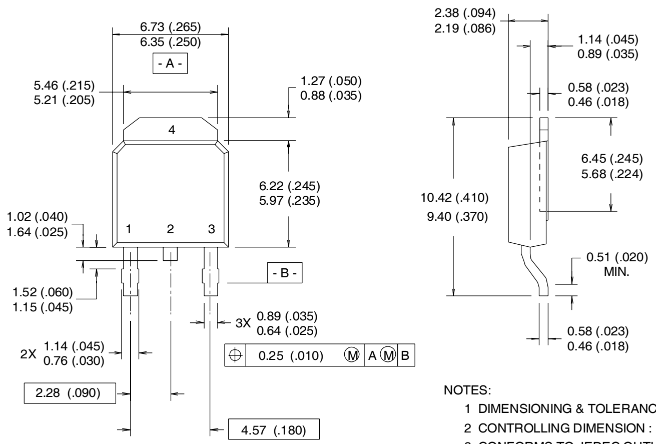


Figure 20. Pulsed Collector Current Test Circuit

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



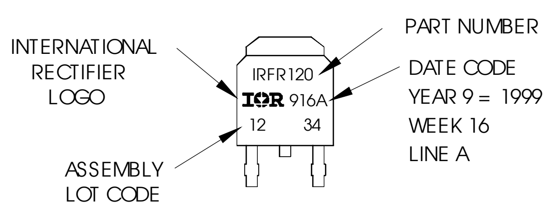
LEAD ASSIGNMENTS
1 - GATE
2 - DRAIN
3 - SOURCE
4 - DRAIN

NOTES:
1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
2 CONTROLLING DIMENSION : INCH.
3 CONFORMS TO JEDEC OUTLINE TO-252AA.
4 DIMENSIONS SHOWN ARE BEFORE SOLDER DIP, SOLDER DIP MAX. +0.16 (.006).

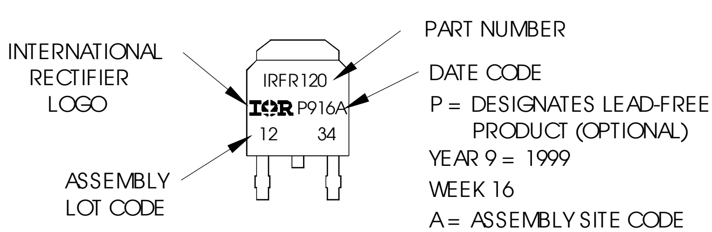
D-Pak (TO-252AA) Part Marking Information (Lead-Free)

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 1999
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates "Lead-Free"



OR



Notes:

① Repetitive rating: V_{GE}=20V; pulse width limited by maximum junction temperature (figure 20)

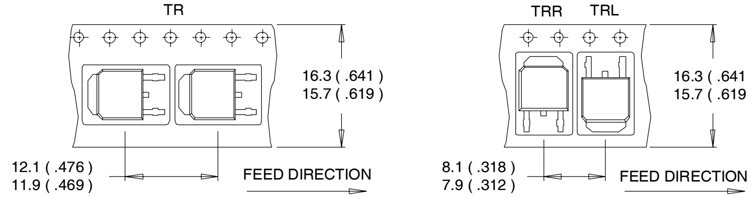
② V_{CC}=80%(V_{CES}), V_{GE}=20V, L=10µH, R_G= 100Ω (figure 19)

③ Pulse width ≤ 80µs; duty factor ≤ 0.1%.

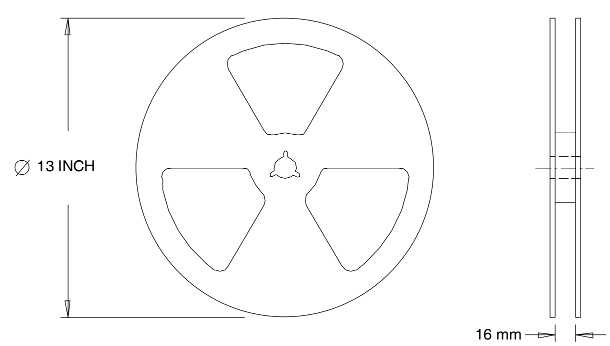
④ Pulse width 5.0µs, single shot.

D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.

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Note: For the most current drawings please refer to the IR website at:
http://www.irf.com/package/